PROCESS FOR PRODUCING AN IC CHIP HAVING A PROTECTIVE LAYER

ABSTRACT OF THE DISCLOSURE

A process for producing an IC chip having a protective layer is provided. The process comprises attaching an adhesive sheet comprising a base material and a layer of a curable resin disposed on one face of the base material to at least one face of an IC chip attached to a circuit substrate under pressure in a manner such that the layer of a curable resin contacts the face of the IC chip and curing the layer of a curable resin.

A uniform protective layer having an accurate shape can be formed on an IC chip in a thin sheet IC circuit such as an IC card efficiently in a simple operation so that formation of cracks in the IC chip can be prevented.

FIGURE: NONE.